



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-04-20
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VN5025AJTR-E	ST0T*VNJ6AFC	A	64BA	2020-04-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	114	mg	Each	ECOPACK 1
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00434803	

Package Designator	Size	Nbr of instances	Shape	
QFP	4.90,3.90,1.55	12	gull wing	
Comment	POWERSO-12. MDF valid for CPs: VN5025AJ-E,VN5025AJTR-E			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.03	die	263
Lead	2.33	soft solder	20456
Antimony trioxide	0.48	encapsulation	4211

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.33	Soft solder	20456
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.332	Soft solder	925030

Material Composition Declaration :						Mfr Item Name	ST0T*VNJ6AFC					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.744	mg	supplier	die	Silicon(Si)	7440-21-3		3.451	mg	921741	30272
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.027	mg	7212	237
				supplier	metallisation	Copper(Cu)	7440-50-8		0.036	mg	9615	316
				supplier	metallisation	Gold(Au)	7440-57-5		0.006	mg	1603	54
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.030	mg	8013	263
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.117	mg	31250	1026
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.021	mg	5609	184
Leadframe	M-004 Copper and its alloys	66.534	mg	supplier	passivation	Silicon oxide	7631-86-9		0.056	mg	14957	491
				supplier	alloy & coating	Copper(Cu)	7440-50-8		66.377	mg	997640	582254
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.031	mg	466	272
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.056	mg	842	491
				supplier	alloy & coating	Silver (Ag)	7440-22-4		0.070	mg	1052	614
Soft solder	Solder	2.521	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	2.332	mg	925030	20456
				supplier	solder	Tin(Sn)	7440-31-5		0.126	mg	49980	1105
				supplier	solder	Silver(Ag)	7440-22-4		0.063	mg	24990	553
				supplier	wire	Gold(Au)	7440-57-5		0.098	mg	1000000	860
Bonding wires	M-008 Precious metals	0.098	mg	supplier	wire	Copper(Cu)	7440-50-8		0.255	mg	1000000	2237
Bonding wires 2	M-004 Copper and its alloys	0.255	mg	supplier	wire	Copper(Cu)	7440-50-8		0.255	mg	1000000	2237
Encapsulation	M-011 Other inorganic materials	39.876	mg	supplier	mold compound	Silica vitreous	60676-86-0		32.818	mg	823001	287877
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		2.791	mg	69992	24482
				supplier	mold compound	Phenol resin	9003-35-4		1.595	mg	39999	13991
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		1.196	mg	29994	10491
				supplier	mold compound	Antimony trioxide	1309-64-4		0.479	mg	12012	4202
				supplier	mold compound	Brominated epoxy resin	40039-93-8		0.798	mg	20012	7000
				supplier	mold compound	Carbon black	1333-86-4		0.199	mg	4990	1746
connections coating	Solder	0.972	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.972	mg	1000000	8526